

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-29. (Canceled)

30 (New). An apparatus for forming a thin film on each of a plurality of substrates, comprising:

a sputtering chamber for carrying out sputtering therein to form the thin film on a surface of each substrate in a sputtering time, and

a conveyer for conveying each of the plurality of substrates one by one for introducing each of the substrates into the sputtering chamber,

wherein said conveyer is capable of conveying one substrate at a time to introduce the substrate in the sputtering chamber so that the sputtering time for carrying out the sputtering for a substrate and an interval time which runs from an end of sputtering for one substrate to a start of sputtering for a next substrate are respectively made constant.

31 (New). The apparatus of Claim 30 further comprising a load lock mechanism for introducing the substrate into the sputtering chamber.

32 (New). The apparatus of Claim 31 wherein said load lock mechanism comprises a load lock chamber, and said load lock mechanism is capable of venting for making the inside room of the load lock chamber atmospheric pressure, accepting the substrate in the load lock chamber, evacuating the inside room of the load lock chamber up to a predetermined degree of vacuum, and

discharging the substrate so that the substrate is introduced into the sputtering chamber, and
wherein said load lock chamber accepts one substrate at one time, so that the discharging of
the substrate is continuously made at a constant interval.

33 (New). The apparatus of Claim 30 wherein the sputtering chamber comprising a substrate
holder having a rotation mechanism and a target holder, and

wherein the substrate holder is capable of holding the substrate in a horizontal state, and the
substrate holder and the target holder are placed so that the target be held opposite to the substrate, a
center axis of the target deviating from a center axis of the substrate.

34 (New). The apparatus of Claim 33 wherein the substrate holder and the target holder are
placed so that a surface of the substrate on which the film is formed and a surface of the target forms
a predetermined angle.

35 (New). The apparatus of Claim 34 wherein the predetermined angle is 10 to 30 degrees.

36 (New). The apparatus of Claim 34 wherein the predetermined angle is 10 to 15 degrees.

37 (New). The apparatus of Claim 33 wherein the substrate holder is rotatable around its
center axis and the number of rotations of the substrate is controlled to be an integer during the film
formation .

38 (New). The apparatus of Claim 37 wherein the substrate holder is rotatable around its

center axis, and the film formation is controlled by detecting a rotation angle of the substrate from the start to the end of the film forming so that the number of rotations of the substrate during the film formation is an integer.

39 (New). The apparatus of Claim 37 wherein a position of the substrate at the start of film forming is detected by a sensor, and, when the same position is detected by the sensor after integer times of rotation of the substrate, the film forming is stopped.

40 (New). A method for preparing a plurality of photo mask blanks which comprises forming a thin film on each of a plurality of substrates in turn, whereby said forming is employed by use of an apparatus, said apparatus comprising:

a sputtering chamber for carrying out sputtering therein to form the thin film on a surface of each substrate in a sputtering time, and

a conveyer for conveying the plurality of substrates one by one for introducing each of the substrates into the sputtering chamber,

wherein said conveyer conveys one substrate at a time to introduce the substrate in the sputtering chamber so that a sputtering time for carrying out the sputtering for a substrate and an interval time which runs from an end of sputtering for one substrate to a start of sputtering for a next substrate are respectively made constant.

41 (New). The method of Claim 40 wherein the apparatus further comprising a load lock mechanism for introducing the substrate into the sputtering chamber,

said load lock mechanism comprising a load lock chamber, wherein said load lock mechanism is capable of venting for making the inside room of the load lock chamber atmospheric pressure, accepting the substrate in the load lock chamber, evacuating the inside room of the load lock chamber up to a predetermined degree of vacuum, and discharging the substrate so that the substrate is introduced into the sputtering chamber, and wherein the load lock chamber accepts one substrate at one time, so that the discharging of the substrate is continuously made at a constant interval.